L	Hits	Search Text	DB	Time stamp
Number -	65857	83/\$.ccls.	USPAT;	2004/06/08
		037 4.0025.	US-PGPUB;	16:02
			EPO; JPO;	ļ
			DERWENT;	
_	166767	29/\$.ccls.	IBM_TDB USPAT;	2004/04/16
	100707	29/3.0013.	US-PGPUB;	10:18
			EPO; JPO;	
			DERWENT;	
	5000	005/4	IBM TDB	2002/04/20
-	5993	225/\$.ccls.	USPAT; US-PGPUB;	2003/04/20 14:19
			EPO; JPO;	
			DERWENT;	
	0255	105/4	IBM_TDB	2002/04/20
_	9355	125/\$.ccls.	USPAT; US-PGPUB;	2003/04/20 14:19
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	61690	451/\$.ccls.	USPAT; US-PGPUB;	2003/04/20 14:19
			EPO; JPO;	14.19
			DERWENT;	
			IBM_TDB	
-	150	tape near3 (bur or burr)	USPAT;	2004/06/08
			US-PGPUB; EPO; JPO;	15:59
			DERWENT;	
			IBM_TDB	
-	1311500	semiconductor or wafer	USPAT;	2004/06/08
			US-PGPUB; EPO; JPO;	15:59
			DERWENT;	
İ	ļ		IBM_TDB	
-	17	(tape near3 (bur or burr)) and	USPAT;	2003/04/20
	:	(semiconductor or wafer)	US-PGPUB; EPO; JPO;	14:22
			DERWENT;	
			IBM_TDB	
-	5	(USPAT;	2003/04/20
		(semiconductor or wafer)) and (83/\$.ccls.	US-PGPUB; EPO; JPO;	14:23
		or 29/\$.ccls. or 225/\$.ccls. or 125/\$.ccls. or	DERWENT;	
			IBM_TDB	
1 -	1667037	cut or cutting	USPAT;	2003/04/20
			US-PGPUB;	14:52
			EPO; JPO; DERWENT;	
			IBM_TDB	
-	63	(tape near3 (bur or burr)) and (cut or	USPAT;	2003/04/20
		cutting)	US-PGPUB; EPO; JPO;	14:24
			DERWENT;	
			IBM_TDB	
-	11	((tape near3 (bur or burr)) and (cut or	USPAT;	2003/04/20
		cutting)) and (semiconductor or wafer)	US-PGPUB; EPO; JPO;	14:25
			DERWENT;	
			IBM_TDB	
-	7	(((tape near3 (bur or burr)) and (cut or	USPAT;	2003/04/20
		cutting)) and (semiconductor or wafer)) not (((tape near3 (bur or burr)) and	US-PGPUB; EPO; JPO;	14:25
		(semiconductor or wafer)) and (83/\$.ccls.	DERWENT;	
		or 29/\$.ccls. or 225/\$.ccls. or	IBM_TDB	
L	<u> </u>	125/\$.ccls. or 451/\$.ccls.))	<u> </u>	

-	98065	156/\$.ccls.	USPAT;	2003/04/20
			US-PGPUB;	14:35
1			EPO; JPO;	
			DERWENT; IBM TDB	
	9	156/\$.ccls. and (tape near3 (bur or	USPAT;	2003/04/20
-		burr))	US-PGPUB;	14:36
			EPO; JPO;	14.50
			DERWENT;	
			IBM TDB	
_	197	tape near4 (bur or burr)	USPAT;	2003/04/20
			US-PGPUB;	14:37
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	19	(tape near4 (bur or burr)) and	USPAT;	2003/04/20
		(semiconductor or wafer)	US-PGPUB;	14:40
			EPO; JPO;	
			DERWENT;	
	1176677		IBM_TDB	2002/04/20
-	1176677	sensor	USPAT;	2003/04/20
		,	US-PGPUB;	14:52
			EPO; JPO; DERWENT;	
			IBM TDB	
_	10	sensor and (tape near3 (bur or burr))	USPAT;	2003/04/20
		Donner and Cape hears (Dar of Dall)	US-PGPUB;	14:47
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	165735	83/\$.ccls. or 29/\$.ccls. or 225/\$.ccls.	USOCR	2003/04/20
		or 125/\$.ccls. or 451/\$.ccls. or		14:50
		156/\$.ccls.		
-	11690	sensor	USOCR	2003/04/20
				14:52
_	644428	cut or cutting	USOCR	2003/04/20
				14:52
-	26	tape near3 (bur or burr)	USOCR	2003/04/20
	27200		,,,,,,,,	14:53
-	27290	semiconductor or wafer	USOCR	2003/04/20 14:52
	31	tane neard (bur or burr)	USOCR	2003/04/20
_	31	tape near4 (bur or burr)	USOCK	14:53
_	1	(tape near4 (bur or burr)) and	USOCR	2003/04/20
	_	(semiconductor or wafer)	OBOOK	14:53
_	36	, · · · · · · · · · · · · · · · · · · ·	USOCR	2003/04/20
			,	14:53
] -	1	(tape near5 (bur or burr)) and	USOCR	2003/04/20
		(semiconductor or wafer)		14:54
-	3451	sensor and (cut or cutting)	USOCR	2003/04/20
				14:54
-	313	, · · · · · · · · · · · · · · · · · · ·	USOCR	2003/04/20
		(semiconductor or wafer)		14:54
-	0	((sensor and (cut or cutting)) and	USOCR	2003/04/20
	:	(semiconductor or wafer)) and (tape near4		14:54
	9	(bur or burr))	HEOCE	2002/04/20
_		(83/\$.ccls. or 29/\$.ccls. or 225/\$.ccls. or 125/\$.ccls. or 451/\$.ccls. or	USOCR	2003/04/20 14:54
		156/\$.ccls. or 451/\$.ccls. or 156/\$.ccls.) and (tape near3 (bur or		11.71
		burr))		
_	7	("4865677" "4925515" "5069738"	USPAT	2003/04/21
	,	"5228944" "5310442" "5472554"		08:27
		"5688354").PN.		_
-	0	6258198.URPN.	USPAT	2003/04/21
				08:28
-	77	tape near5 (bur or burr)	USPAT;	2003/04/21
•			US-PGPUB;	08:35
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	<u>[</u>

<u></u>				
-	2	(tape near5 (bur or burr)) and sensor	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/04/21 08:35
			IBM TDB	
-	4290	((83/13) or (83/23) or (83/27) or (83/28) or (83/34) or (83/36) or (83/61) or (83/73) or (83/75) or (83/76.7) or (83/78) or (83/365) or (83/401) or (83/523) or (83/663) or (83/922) or	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/21 08:55
_	4682	(83/929.1)).CCLS. ((156/253) or (156/267) or (156/353) or (156/522) or (156/64) or (156/250)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/04/21 08:55
			IBM TDB	
_	5867	((451/41) or (451/63) or (451/28) or (451/6) or (451/285) or (451/287) or (451/288) or (451/413) or (451/402)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/21 08:56
	0	(83/28) or (83/34) or (83/36) or (83/61) or (83/73) or (83/75) or (83/76.7) or (83/78) or (83/365) or (83/401) or (83/523) or (83/663) or (83/922) or (83/929.1)).CCLS.) and (((156/253) or (156/267) or (156/353) or (156/522) or (156/64) or (156/250)).CCLS.) and (((451/41) or (451/63) or (451/28) or (451/6) or (451/285) or (451/287) or (451/288) or (451/413) or	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/21 08:56
-	29	(451/402)).CCLS.) (((83/13) or (83/23) or (83/27) or (83/28) or (83/34) or (83/36) or (83/61) or (83/73) or (83/75) or (83/76.7) or (83/78) or (83/365) or (83/401) or (83/523) or (83/663) or (83/922) or (83/929.1)).CCLS.) and (((156/253) or (156/267) or (156/250)).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/21 08:56
	654047	detect or detector	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/21 09:36
_	77	tape near5 (bur or burr)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/21 09:36
_	1	(detect or detector) and (tape near5 (bur or burr))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/21 09:36
_	77447	detect or detector	USOCR	2003/04/21 09:36
-	36	tape near5 (bur or burr)	USOCR	2003/04/21
_	3	(detect or detector) and (tape near5 (bur or burr))	USOCR	09:36 2003/04/21 09:36
-	2	("4865677").PN.	USPAT; US-PGPUB;	2003/11/02 13:51
			EPO; JPO; DERWENT;	
-	3	("4510009" "4680079" "4696712").PN.	IBM_TDB USPAT	2003/11/02
_	8	4865677.URPN.	USPAT	13:52 2003/11/02 13:55

	210540	I tama	IICDAT	2002/11/02
-	210549	tape	USPAT	2003/11/02 13:55
-	7	4865677.URPN. and tape	USPAT	2003/11/02 14:13
_	2	("6116988").PN.	USPAT;	2003/11/02
			US-PGPUB;	14:14
			EPO; JPO;	
		•	DERWENT; IBM TDB	
_	210549	tape and tape	USPAT;	2003/11/02
			US-PGPUB;	14:14
•			EPO; JPO;	
			DERWENT; IBM TDB	
_	1	tape and (("6116988").PN.)	USPAT;	2003/11/02
			US-PGPUB;	14:30
			EPO; JPO;	
			DERWENT; IBM TDB	
_	2	("5422163").PN.	USPAT;	2003/11/02
			US-PGPUB;	14:30
		•	EPO; JPO;	
			DERWENT; IBM TDB	
_	1	tape and (("5422163").PN.)	USPAT;	2003/11/02
			US-PGPUB;	14:45
			EPO; JPO;	
			DERWENT; IBM TDB	
_	1	(tape and (("5422163").PN.)) and cut	USPAT;	2003/11/02
			US-PGPUB;	14:46
			EPO; JPO;	
			DERWENT; IBM TDB	
_	. 3	("3909915").PN.	USPAT;	2003/11/02
			US-PGPUB;	14:47
		,	EPO; JPO;	
			DERWENT;	
_	· 0	(("3909915").PN.) and tape and cut	USPAT;	2003/11/02
			US-PGPUB;	14:47
			EPO; JPO; DERWENT;	
		,	IBM TDB	
_	1	(("3909915").PN.) and tape	USPAT;	2003/11/02
			US-PGPUB;	14:47
			EPO; JPO; DERWENT;	
			IBM_TDB	
-	2	("5688354").PN.	USPAT;	2003/11/02
]			US-PGPUB; EPO; JPO;	14:47
			DERWENT;	
			IBM_TDB	
-	1	(("5688354").PN.) and tape and cut	USPAT;	2003/11/02
			US-PGPUB; EPO; JPO;	14:48
			DERWENT;	
			IBM_TDB	
-	0	, · · · · · · · · · · · · · · · · · · ·	USPAT;	2003/11/02
		burr	US-PGPUB; EPO; JPO;	14:52
			DERWENT;	,
			IBM_TDB	
-	6	, , , , , , , , , , , , , , , , , , , ,	USPAT;	2003/11/02
		("4680079")).PN.	US-PGPUB; EPO; JPO;	14:53
			DERWENT;	
	<u>L</u> .	<u> </u>	IBM_TDB	
				

		·		
_	1670	tape and cut and burr	USPAT;	2003/11/02
			US-PGPUB;	14:53
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	0	((("4510009") or ("4696712") or	USPAT;	2003/11/02
		("4680079")).PN.) and (tape and cut and	US-PGPUB;	14:53
		burr)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	172177	29/\$.ccls.	USPĀT;	2004/04/16
			US-PGPUB;	10:18
			EPO; JPO;	
			DERWENT;	
			IBM TDB	l i
_	27332	tape near3 (remove or removing or cut or	USPAT;	2004/04/16
		cutting)	US-PGPUB;	10:19
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	348610	wafer	USPAT;	2004/04/16
			US-PGPUB;	10:19
			EPO; JPO;	
			DERWENT;	1
			IBM TDB	
-	3433833	sensor or detect or sensing or sensed or	USPAT;	2004/04/16
		detecting or detected	US-PGPUB;	10:19
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	1364	(tape near3 (remove or removing or cut or	USPAT;	2004/04/16
		cutting)) and wafer	US-PGPUB;	10:20
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	90	((tape near3 (remove or removing or cut	USPAT;	2004/04/16
		or cutting)) and wafer) and 29/\$.ccls.	US-PGPUB;	10:20
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	22	(((tape near3 (remove or removing or cut	USPAT;	2004/06/08
		or cutting)) and wafer) and 29/\$.ccls.)	US-PGPUB;	16:04
		and (sensor or detect or sensing or	EPO; JPO;	
		sensed or detecting or detected)	DERWENT;	
			IBM TDB	
-	2173	backgrinding or (back near2 grinding)	USPAT;	2004/04/16
			US-PGPUB;	10:22
			EPO; JPO;	
			DERWENT;	
			IBM TDB	1
_	6	(((tape near3 (remove or removing or cut	USPĀT;	2004/04/16
		or cutting)) and wafer) and 29/\$.ccls.)	US-PGPUB;	10:22
		and (backgrinding or (back near2	EPO; JPO;	
	1	grinding))	DERWENT;	
			IBM TDB	
-	152025	438/\$.ccls.	USPAT;	2004/06/08
			US-PGPUB;	15:59
			EPO; JPO;]
			DERWENT;	
			IBM_TDB	
-	3710	438/\$.ccls.	USOCR	2004/06/08
]		,		16:03
 - '	162	tape near3 (bur or burr)	USPAT;	2004/06/08
			US-PGPUB;	16:03
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	26	tape near3 (bur or burr)	USOCR	2004/06/08
				16:03
		· · · · · · · · · · · · · · · · · · ·	L	

	1.00000		110D3M	1 2004/06/08
_	1498239	semiconductor or wafer	USPAT; US-PGPUB;	2004/06/08 16:03
			EPO; JPO;	10.03
			DERWENT;	
			IBM TDB	
_	27277	semiconductor or wafer	USOCR	2004/06/08
				16:02
_	0		USPAT;	2004/06/08
		detected or detecting	US-PGPUB; EPO; JPO;	16:01
			DERWENT;	
			IBM TDB	
_	5166058	sensor or sensing or sensed or detect or	USPAT;	2004/06/08
		detected or detecting or determine or	US-PGPUB;	16:02
		determined or determining or encoder	EPO; JPO;	
			DERWENT; IBM TDB	
_	27277	semiconductor or wafer	USOCR	2004/06/08
	2,2,,	Semilosinadosof of wardi		16:02
_	1498239	semiconductor or wafer	USPAT;	2004/06/08
			US-PGPUB;	16:03
			EPO; JPO;	
			DERWENT; IBM TDB	
_	26	tape near3 (bur or burr)	USOCR	2004/06/08
				17:28
_	162	tape near3 (bur or burr)	USPAT;	2004/06/08
			US-PGPUB;	16:07
			EPO; JPO;	
			DERWENT; IBM TDB	
_	3710	438/\$.ccls.	USOCR	2004/06/08
	, ,,,,,			16:03
_	152025	438/\$.ccls.	USPAT;	2004/06/08
			US-PGPUB;	16:03
			EPO; JPO;	
			DERWENT; IBM TDB	
_	1383	((tape near3 (remove or removing or cut	USPAT;	2004/06/08
		or cutting)) and wafer)	US-PGPUB;	16:08
			EPO; JPO;	
			DERWENT;	
_	43	((tape near3 (remove or removing or cut	IBM_TDB USOCR	2004/06/08
	43	or cutting)) and wafer)	OBOCK	16:04
_	588449		USOCR	2004/06/08
		detected or detecting or determine or		16:07
	_	determined or determining or encoder	*****	2004/05/22
_	2	(and a same)	USPAT;	2004/06/08 16:07
		438/\$.ccls.	US-PGPUB; EPO; JPO;	10.07
			DERWENT;	
			IBM_TDB	
-	0	(tage transfer to the tage to tage to the tage to tag	USOCR	2004/06/08
	100	438/\$.ccls.	HEOGR	16:08
_	106	438/\$.ccls. and tape	USOCR	2004/06/08 16:08
_	689	(tape near4 (remove or removing or cut or	USPAT;	2004/06/08
	_	cutting)) and (tape and 438/\$.ccls.)	US-PGPUB;	16:10
			EPO; JPO;	
			DERWENT;	
_	9	Itane neard (remove or removing or cut or	IBM_TDB USOCR	2004/06/08
	9	(tape near4 (remove or removing or cut or cutting)) and (438/\$.ccls. and tape)	02000	16:10
-	21	438/\$.ccls. and (bur or burr)	USOCR	2004/06/08
				16:33
-	775	438/\$.ccls. and (bur or burr)	USPAT;	2004/06/08
			US-PGPUB;	16:35
			EPO; JPO; DERWENT;	
			IBM TDB	
	L	<u> </u>		<u> </u>

-	26	(438/\$.ccls. and (bur or burr)) and	USPAT;	2004/06/08
		((tape near4 (remove or removing or cut	US-PGPUB;	16:35
		or cutting)) and (tape and 438/\$.ccls.))	EPO; JPO;	
			DERWENT;	
	İ		IBM_TDB	}
_	14	tape near2 (bur or burr)	USOCR	2004/06/08
				17:29
_	109	tape near2 (bur or burr)	USPAT;	2004/06/08
			US-PGPUB;	17:29
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	